

PIC16(L)F170X Memory Programming Specification

This document includes the programming specifications for the following devices:

• PIC16F1703 • PIC16LF1703

• PIC16F1704 • PIC16LF1704

PIC16F1705
 PIC16LF1705

PIC16F1707
 PIC16LF1707

PIC16F1708
 PIC16LF1708

• PIC16F1709 • PIC16LF1709

1.0 OVERVIEW

The device can be programmed using either the high-voltage In-Circuit Serial Programming™ (ICSP™) method or the low-voltage ICSP method.

1.1 Hardware Requirements

1.1.1 HIGH-VOLTAGE ICSP PROGRAMMING

In High-Voltage ICSP mode, the device requires two programmable power supplies: one for VDD and one for the MCLR/VPP pin.

1.1.2 LOW-VOLTAGE ICSP PROGRAMMING

In Low-Voltage ICSP mode, the PIC16(L)F170X devices can be programmed using a single VDD source in the operating range. The $\overline{\text{MCLR}/\text{VPP}}$ pin does not have to be brought to a different voltage, but can instead be left at the normal operating voltage.

1.1.2.1 Single-Supply ICSP Programming

The LVP bit in Configuration Word 2 enables single-supply (low-voltage) ICSP programming. The LVP bit defaults to a '1' (enabled) from the factory. The LVP bit may only be programmed to '0' by entering the High-Voltage ICSP mode, where the MCLR/VPP pin is raised to VIHH. Once the LVP bit is programmed to a '0', only the High-Voltage ICSP mode is available and only the High-Voltage ICSP mode can be used to program the device.

Note 1: The High-Voltage ICSP mode is always available, regardless of the state of the LVP bit, by applying VIHH to the MCLR/VPP pin.

2: While in Low-Voltage ICSP mode, MCLR is always enabled, regardless of the MCLRE bit, and the port pin can no longer be used as a general purpose input.

1.2 Pin Utilization

Five pins are needed for ICSP programming. The pins are listed in Table 1-1.

TABLE 1-1: PIN DESCRIPTIONS DURING PROGRAMMING FOR PIC16(L)F170X

Pin Name	During Programming				
riii Naiile	Function	Pin Type	Pin Description		
ICSPCLK	ICSPCLK	1	Clock Input – Schmitt Trigger Input		
ICSPDAT	ICSPDAT	I/O	Data Input/Output – Schmitt Trigger Input		
MCLR/VPP	Program/Verify mode	P ⁽¹⁾	Program Mode Select/Programming Power Supply		
VDD	VDD	Р	Power Supply		
Vss	Vss	Р	Ground		

Legend: I = Input, O = Output, P = Power

Note 1: The programming high voltage is internally generated. To activate the Program/Verify mode, high voltage needs to be applied to MCLR input. Since the MCLR is used for a level source, MCLR does not draw any significant current.

2.0 DEVICE PINOUTS

The pin diagrams for the PIC16(L)F170X family are shown in Figure 2-1 to Figure 2-4. The pins that are required for programming are listed in Table 1-1 and shown in bold lettering in the pin diagrams.

FIGURE 2-1: 14-PIN DIAGRAM FOR PIC16(L)F1703/4/5

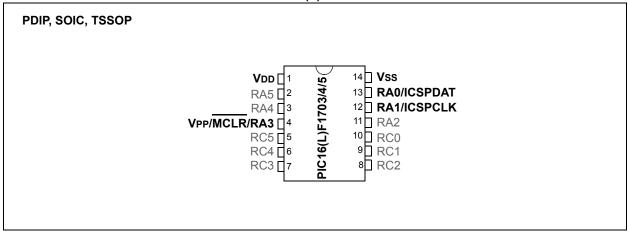


FIGURE 2-2: 16-PIN PACKAGE DIAGRAM FOR PIC16(L)F1703/4/5

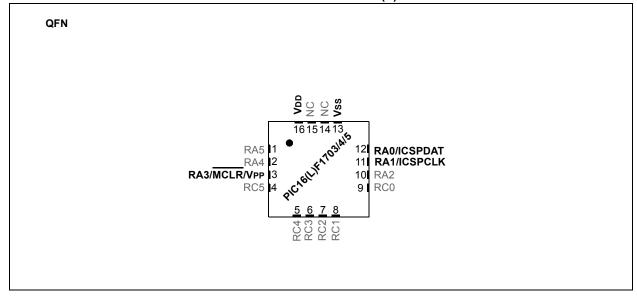
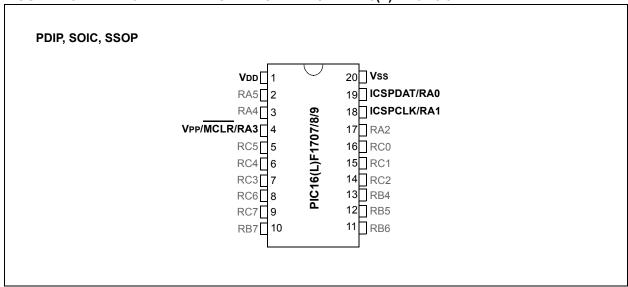
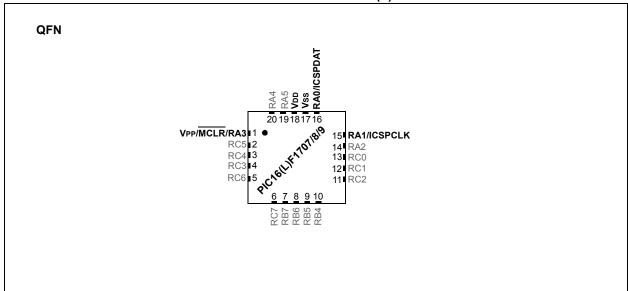


FIGURE 2-3: 20-PIN PACKAGE DIAGRAM FOR PIC16(L)F1707/8/9



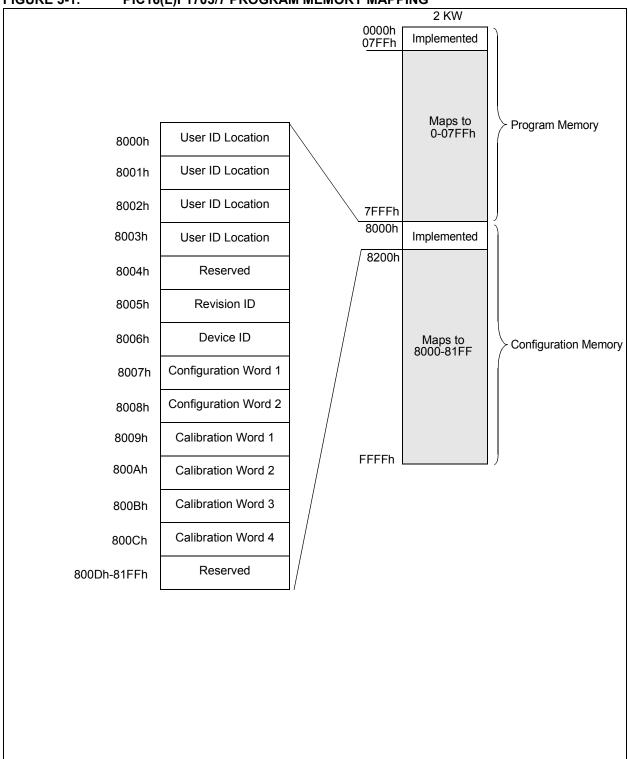


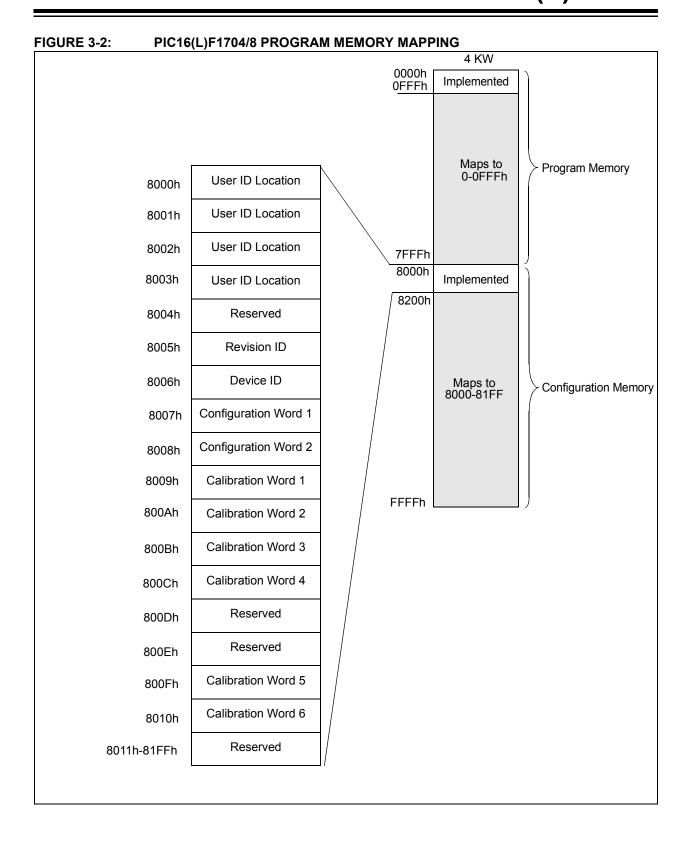


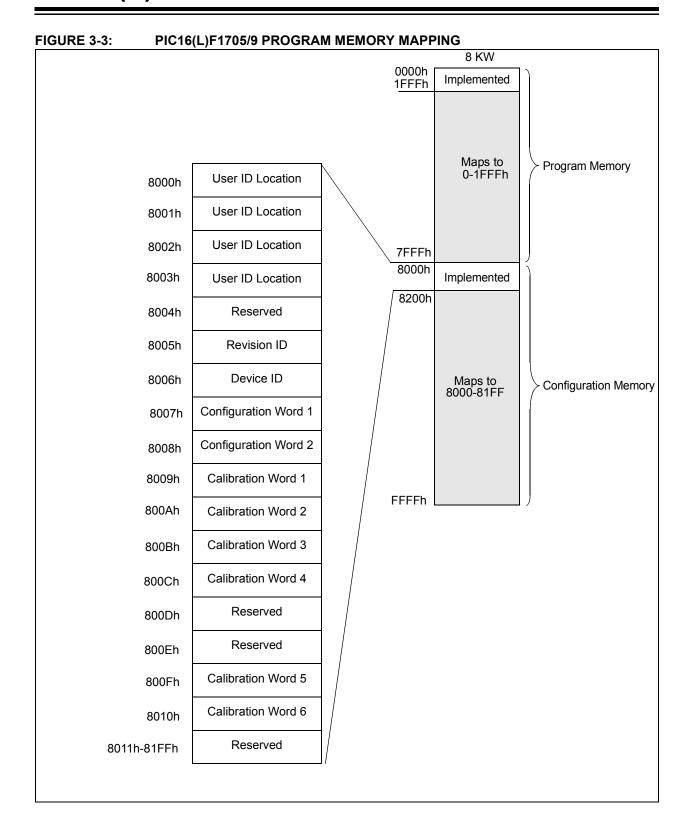
3.0 MEMORY MAP

The memory is broken into two sections: program memory and configuration memory.

FIGURE 3-1: PIC16(L)F1703/7 PROGRAM MEMORY MAPPING







3.1 User ID Location

A user may store identification information (user ID) in four designated locations. The user ID locations are mapped to 8000h-8003h. Each location is 14 bits in length. Code protection has no effect on these memory locations. Each location may be read with code protection enabled or disabled.

Note: MPLAB® IDE only displays the seven Least Significant bits (LSb) of each user ID location. The upper bits are not read. It

ID location. The upper bits are not read. It is recommended that only the seven LSbs be used if MPLAB IDE is the primary tool used to read these addresses.

3.2 Device/Revision ID

The 14-bit device ID word is located at 8006h and the 14-bit revision ID is located at 8005h. These locations are read-only and cannot be erased or modified.

REGISTER 3-1: DEVICEID: DEVICE ID REGISTER⁽¹⁾

R	R	R	R	R	R				
	DEV<13:8>								
bit 13					bit 8				

R	R	R	R	R	R	R	R	
DEV<7:0>								
bit 7 bi								

Legend:

R = Readable bit

'0' = Bit is cleared '1' = Bit is set x = Bit is unknown

bit 13-0 **DEV<13:0>:** Device ID bits

Refer to Table 3-1 to determine what these bits will read on which device. A value of 3FFFh is invalid.

Note 1: This location cannot be written.

REGISTER 3-2: REVISIONID: REVISION ID REGISTER⁽¹⁾

R	R	R	R	R	R			
REV<13:8>								
bit 13					bit 8			

R	R	R	R	R	R	R	R		
REV<7:0>									
bit 7									

Legend:

R = Readable bit

'0' = Bit is cleared '1' = Bit is set x = Bit is unknown

bit 13-0 **REV<13:0>:** Revision ID bits

These bits are used to identify the device revision.

Note 1: This location cannot be written.

TABLE 3-1: DEVICE ID VALUES (PIC16(L)F170X)

DEVICE	Device ID	Revision ID
PIC16F1703	3061h	2xxxh
PIC16LF1703	3063h	2xxxh
PIC16F1704	3043h	2xxxh
PIC16LF1704	3045h	2xxxh
PIC16F1705	3055h	2xxxh
PIC16LF1705	3057h	2xxxh
PIC16F1707	3060h	2xxxh
PIC16LF1707	3062h	2xxxh
PIC16F1708	3042h	2xxxh
PIC16LF1708	3044h	2xxxh
PIC16F1709	3054h	2xxxh
PIC16LF1709	3056h	2xxxh

3.3 Configuration Words

The device has two Configuration Words, Configuration Word 1 (8007h) and Configuration Word 2 (8008h). The individual bits within these Configuration Words are used to enable or disable device functions such as the Brown-out Reset, code protection and Power-up Timer.

3.4 Calibration Words

The internal calibration values are factory calibrated and stored in the Calibration Word locations. See Figure 3-1 for address information.

The Calibration Words do not participate in erase operations. The device can be erased without affecting the Calibration Words.

REGISTER 3-3: CONFIGURATION WORD 1

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	U-1
FCMEN	IESO	CLKOUTEN	BOREN<1:0>		_
bit 13					bit 8

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1 ⁽³⁾	R/P-1	R/P-1
CP	MCLRE	PWRTE	WDTE<1:0>		FOSC<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	n = Value when blank or after Bulk Erase

bit 13	FCMEN: Fail-Safe Clock Monitor Enable bit
	1 = ON Fail-Safe Clock Monitor is enabled
	0 = OFF Fail-Safe Clock Monitor is disabled
bit 12	IESO: Internal External Switchover bit
	1 = ON Internal/External Switchover mode is enal

1 = ON Internal/External Switchover mode is enabled 0 = OFF Internal/External Switchover mode is disabled

bit 11 CLKOUTEN: Clock Out Enable bit

1 = OFF CLKOUT function is disabled. I/O or oscillator function on CLKOUT

0 = ON CLKOUT function is enabled on CLKOUT

bit 10-9 **BOREN<1:0>:** Brown-out Reset Enable bits⁽¹⁾

11 = ON Brown-out Reset enabled

10 = SLEEP Brown-out Reset enabled during operation and disabled in Sleep
01 = SBODEN Brown-out Reset controlled by SBOREN bit of the BORCON register

00 = OFF Brown-out Reset disabled

bit 8 Unimplemented: Read as '1'

bit 7 CP: Code Protection bit⁽²⁾

1 = OFF Program memory code protection is disabled

0 = ON Program memory code protection is enabled

bit 6 MCLRE: MCLR/VPP Pin Function Select bit

 $\frac{\text{If LVP bit} = 1 \quad (ON)}{\text{This bit is ignored.}}$

If LVP bit = 0 (OFF):

 $1 = ON \overline{MCLR/VPP}$ pin function is \overline{MCLR} ; Weak pull-up enabled.

0 = OFF MCLR/VPP pin function is digital input; MCLR internally disabled; Weak pull-up under control of port pin's WPU control bit.

bit 5 **PWRTE:** Power-up Timer Enable bit⁽¹⁾

1 = OFF PWRT disabled 0 = ON PWRT enabled

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.

2: The entire program memory will be erased when the code protection is turned off.

3: Bit 2 of Configuration Word 1 is unimplemented and reads '1' on PIC16(L)F1703/7 devices.

REGISTER 3-3: CONFIGURATION WORD 1 (CONTINUED)

bit 4-3 WDTE<1:0>: Watchdog Timer Enable bit 11 = ONWDT enabled 10 = SLEEP WDT enabled while running and disabled in Sleep 01 = SWDTEN WDT controlled by the SWDTEN bit in the WDTCON register 00 = OFFWDT disabled bit 2-0 FOSC<2:0>: Oscillator Selection bits (PIC16(L)F1704/8 and PIC16(L)F1705/9) External Clock, High-Power mode: CLKIN on OSC1/CLKIN 111 = ECHExternal Clock, Medium-Power mode: CLKIN on OSC1/CLKIN 110 = ECMExternal Clock, Low-Power mode: CLKIN on OSC1/CLKIN 101 = ECL100 = INTOSC Internal HFINTOSC, I/O function on OSC1/CLKIN 011 = EXTRCExternal RC oscillator, RC function on OSC1/CLKIN High-speed crystal/resonator on OSC2/CLKOUT pin and OSC1/CLKIN 010 = HS001 = XTCrystal/resonator on OSC2/CLKOUT pin and OSC1/CLKIN 000 = LPLow-power crystal on OSC2/CLKOUT pin and OSC1/CLKIN **FOSC<1:0>**(3): Oscillator Selection bits (PIC16(L)F1703/7) 11 = ECHExternal Clock, High-Power mode: CLKIN on OSC1/CLKIN 10 = ECMExternal Clock, Medium-Power mode: CLKIN on OSC1/CLKIN External Clock, Low-Power mode: CLKIN on OSC1/CLKIN 01 = ECL

Note 1: Enabling Brown-out Reset does not automatically enable Power-up Timer.

00 = INTOSC

The entire program memory will be erased when the code protection is turned off.

3: Bit 2 of Configuration Word 1 is unimplemented and reads '1' on PIC16(L)F1703/7 devices.

Internal HFINTOSC, I/O function on OSC1/CLKIN

REGISTER 3-4: CONFIGURATION WORD 2

R/P-1	R/P-1	R/P-1	R/P-1	R/P-1	R/P-1
LVP	DEBUG	LPBOR	BORV	STVREN	PLLEN
bit 13					bit 8

R/P-1	U-1	U-1	U-1	U-1	R/P-1	R/P-1	R/P-1
ZCDDIS	_	_	_	_	PPS1WAY	WRT<1:0>	
bit 7							bit 0

Legend:		
R = Readable bit	P = Programmable bit	U = Unimplemented bit, read as '1'
'0' = Bit is cleared	'1' = Bit is set	n = Value when blank or after Bulk Erase

<u> </u>	tio didated 1 Bit to dot 11 Value When Blank of alter Bank Erado
bit 13	LVP: Low-Voltage Programming Enable bit ⁽¹⁾
	1 = ON <u>Low-voltage programming enabled</u>
	0 = OFF MCLR/VPP must be used for programming high voltage
bit 12	DEBUG: In-Circuit Debugger Mode bit
	1 = OFF In-Circuit Debugger disabled, ICSPCLK and ICSPDAT are general purpose I/O pins
	0 = ON In-Circuit Debugger enabled, ICSPCLK and ICSPDAT are dedicated to the debugger
bit 11	LPBOR: Low-Power Brown-out Reset Enable bit
	1 = OFF Low-Power Brown-out is disabled 0 = ON Low-Power Brown-out is enabled
1 11 40	
bit 10	BORV: Brown-out Reset Voltage Selection bit ⁽²⁾
	1 = LOW Brown-out Reset voltage (Vbor), low trip point selected 0 = HIGH Brown-out Reset voltage (Vbor), high trip point selected
bit 9	STVREN: Stack Overflow/Underflow Reset Enable bit
DIL 9	1 = ON Stack Overflow or Underflow will cause a Reset
	0 = OFF Stack Overflow or Underflow will not cause a Reset
bit 8	PLLEN: PLL Enable bit
2.0	1 = ON 4xPLL enabled
	0 = OFF 4xPLL disabled
bit 7	ZCDDIS: Zero-Cross Detect Disable bit
	1 = ON Zero-cross detection is disabled on POR. Zero cross detection can be controlled by soft-
	ware.
	0 = OFF Zero-cross detection is always enabled. Software cannot disable zero cross detection.
bit 6-3	Unimplemented: Read as '1'
bit 2	PPS1WAY: PPSLOCK One-Way Set Enable bit
	1 = ON The PPSLOCK bit is permanently set after the first access sequence that sets it.
	0 = OFF The PPSLOCK bit can be set and cleared as needed by the PPSLOCK access sequence.

Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.

2: See Vbor parameter for specific trip point voltages.

REGISTER 3-4: CONFIGURATION WORD 2 (CONTINUED)

bit 1-0 WRT<1:0>: Flash Memory Self-Write Protection bits

2 kW Flash memory: (PIC16(L)F1703/7):

- 11 = OFF Write protection off
- 10 = BOOT 000h to 0FFh write-protected, 100h to 7FFh may be modified by PMCON control
- 01 = HALF 000h to 3FFh write-protected, 400h to 7FFh may be modified by PMCON control
- 00 = ALL 000h to 7FFh write-protected, no addresses may be modified by PMCON control

4 kW Flash memory: (PIC16(L)F1704/8):

- 11 = OFF Write protection off
- 10 = BOOT 000h to 1FFh write-protected, 200h to FFFh may be modified by PMCON control
- 01 = HALF 000h to 7FFh write-protected, 800h to FFFh may be modified by PMCON control
- 00 = ALL 000h to FFFh write-protected, no addresses may be modified by PMCON control

8 kW Flash memory: (PIC16(L)F1705/9)

- 11 = OFF Write protection off
- 10 = BOOT 0000h to 01FFh write-protected, 0200h to 1FFFh may be modified by PMCON control
- 01 = HALF 0000h to 0FFFh write-protected, 1000h to 1FFFh may be modified by PMCON control
- 00 = ALL 0000h to 1FFFh write-protected, no addresses may be modified by PMCON control
- Note 1: The LVP bit cannot be programmed to '0' when Programming mode is entered via LVP.
 - **2:** See Vbor parameter for specific trip point voltages.

4.0 PROGRAM/VERIFY MODE

In Program/Verify mode, the program memory and the configuration memory can be accessed and programmed in serial fashion. ICSPDAT and ICSPCLK are used for the data and the clock, respectively. All commands and data words are transmitted LSb first. Data changes on the rising edge of the ICSPCLK and is latched on the falling edge. In Program/Verify mode, both the ICSPDAT and ICSPCLK are Schmitt Trigger inputs. The sequence that enters the device into Program/Verify mode places all other logic into the Reset state. Upon entering Program/Verify mode, all I/Os are automatically configured as high-impedance inputs and the address is cleared.

4.1 High-Voltage Program/Verify Mode Entry and Exit

There are two different methods of entering Program/ Verify mode via high-voltage:

- VPP First entry mode
- VDD First entry mode

4.1.1 VPP – FIRST ENTRY MODE

To enter Program/Verify mode via the VPP-first method, the following sequence must be followed:

- 1. Hold ICSPCLK and ICSPDAT low. All other pins should be unpowered.
- 2. Raise the voltage on MCLR from 0V to VIHH.
- 3. Raise the voltage on VDD from 0V to the desired operating voltage.

The VPP-first entry prevents the device from executing code prior to entering Program/Verify mode. For example, when the Configuration Word has MCLR disabled (MCLRE = 0), the power-up time is disabled (PWRTE = 0), the internal oscillator is selected (Fosc = 100), and RA0 and RA1 are driven by the user application, the device will execute code. Since this may prevent entry, VPP-first entry mode is strongly recommended. See the timing diagram in Figure 8-2.

4.1.2 VDD – FIRST ENTRY MODE

To enter Program/Verify mode via the VDD-first method, the following sequence must be followed:

- Hold ICSPCLK and ICSPDAT low.
- Raise the voltage on VDD from 0V to the desired operating voltage.
- Raise the voltage on MCLR from VDD or below to VIHH.

The VDD-first method is useful when programming the device when VDD is already applied, for it is not necessary to disconnect VDD to enter Program/Verify mode. See the timing diagram in Figure 8-1.

4.1.3 PROGRAM/VERIFY MODE EXIT

To exit Program/Verify mode take MCLR to VDD or lower (VIL). See Figures 8-3 and 8-4.

4.2 Low-Voltage Programming (LVP) Mode

The Low-Voltage Programming mode allows the PIC16(L)F170X devices to be programmed using VDD only, without high voltage. When the LVP bit of the Configuration Word 2 register is set to '1', the low-voltage ICSP programming entry is enabled. To disable the Low-Voltage ICSP mode, the LVP bit must be programmed to '0'. This can only be done while in the High-Voltage Entry mode.

Entry into the Low-Voltage ICSP Program/Verify mode requires the following steps:

- 1. MCLR is brought to VIL.
- A 32-bit key sequence is presented on ICSPDAT, while clocking ICSPCLK.

The key sequence is a specific 32-bit pattern, '0100 1101 0100 0011 0100 1000 0101 0000' (more easily remembered as MCHP in ASCII). The device will enter Program/Verify mode only if the sequence is valid. The Least Significant bit of the Least Significant nibble must be shifted in first.

Once the key sequence is complete, $\overline{\text{MCLR}}$ must be held at V_{IL} for as long as Program/Verify mode is to be maintained.

For low-voltage programming timing, see Figures 8-8 and 8-9.

Exiting Program/Verify mode is done by no longer driving MCLR to VIL. See Figures 8-8 and 8-9.

Note: To enter LVP mode, the LSb of the Least Significant nibble must be shifted in first. This differs from entering the key sequence on other parts.

4.3 Program/Verify Commands

These devices implement 13 programming commands, each six bits in length. The commands are summarized in Table 4-1.

Commands that have data associated with them are specified to have a minimum delay of TDLY between the command and the data. After this delay, 16 clocks are required to either clock in or clock out the 14-bit data word. The first clock is for the Start bit and the last clock is for the Stop bit.

TABLE 4-1: COMMAND MAPPING FOR PIC16(L)F170X

Command				Маррі	Data/Note			
		Binary (MSb LSb)						
Load Configuration	Х	0	0	0	0	0	00h	0, data (14), 0
Load Data For Program Memory	Х	0	0	0	1	0	02h	0, data (14), 0
Read Data From Program Memory	Х	0	0	1	0	0	04h	0, data (14), 0
Increment Address	Х	0	0	1	1	0	06h	_
Reset Address	Х	1	0	1	1	0	16h	_
Begin Internally Timed Programming	Х	0	1	0	0	0	08h	_
Begin Externally Timed Programming	Х	1	1	0	0	0	18h	_
End Externally Timed Programming	Х	0	1	0	1	0	0Ah	_
Bulk Erase Program Memory	Х	0	1	0	0	1	09h	Internally Timed
Row Erase Program Memory	Х	1	0	0	0	1	11h	Internally Timed

4.3.1 LOAD CONFIGURATION

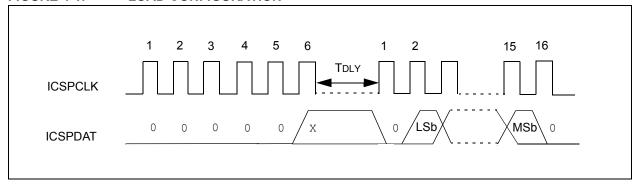
The Load Configuration command is used to access the configuration memory (User ID Locations, Configuration Words, Calibration Words). The Load Configuration command sets the address to 8000h and loads the data latches with one word of data (see Figure 4-1).

After issuing the Load Configuration command, use the Increment Address command until the proper address to be programmed is reached. The address is then programmed by issuing either the Begin Internally Timed Programming or Begin Externally Timed Programming command.

Note: Externally timed writes are not supported for Configuration and Calibration bits. Any externally timed write to the Configuration or Calibration Word will have no effect on the targeted word.

The only way to get back to the program memory (address 0) is to exit Program/Verify mode or issue the Reset Address command after the configuration memory has been accessed by the Load Configuration command.

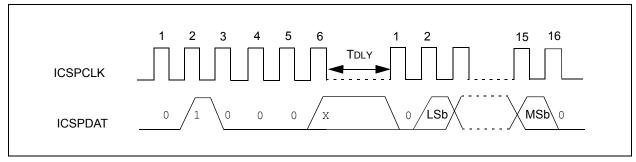
FIGURE 4-1: LOAD CONFIGURATION



4.3.2 LOAD DATA FOR PROGRAM MEMORY

The Load Data for Program Memory command is used to load one 14-bit word into the data latches. The word programs into program memory after the Begin Internally Timed Programming or Begin Externally Timed Programming command is issued (see Figure 4-2).

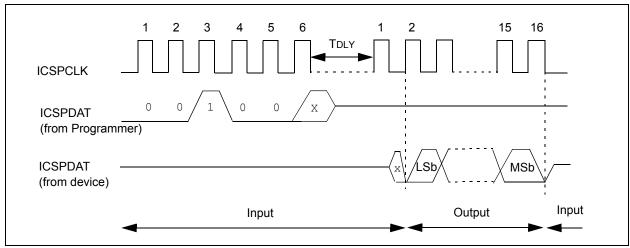
FIGURE 4-2: LOAD DATA FOR PROGRAM MEMORY



4.3.3 READ DATA FROM PROGRAM MEMORY

The Read Data from Program Memory command will transmit data bits out of the program memory map currently accessed, starting with the second rising edge of the clock input. The ICSPDAT pin will go into Output mode on the first falling clock edge, and it will revert to Input mode (high-impedance) after the 16th falling edge of the clock. If the program memory is code-protected (\overline{CP}) , the data will be read as zeros (see Figure 4-3).

FIGURE 4-3: READ DATA FROM PROGRAM MEMORY

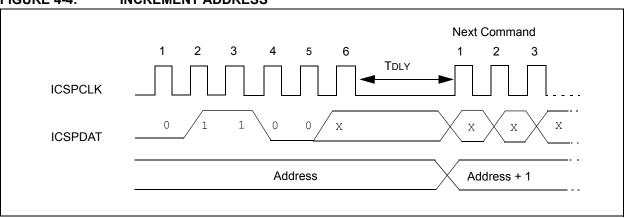


4.3.4 INCREMENT ADDRESS

The address is incremented when this command is received. It is not possible to decrement the address. To reset this counter, the user must use the Reset Address command or exit Program/Verify mode and re-enter it.

If the address is incremented from address 7FFFh, it will wrap-around to location 0000h. If the address is incremented from FFFFh, it will wrap-around to location 8000h (see Figure 4-4).

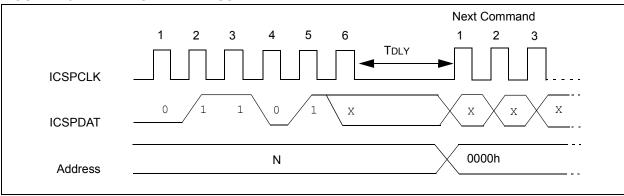
FIGURE 4-4: INCREMENT ADDRESS



4.3.5 RESET ADDRESS

The Reset Address command will reset the address to 0000h, regardless of the current value. The address is used in program memory or the configuration memory (see Figure 4-5).

FIGURE 4-5: RESET ADDRESS



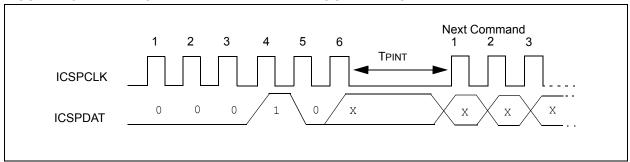
4.3.6 BEGIN INTERNALLY TIMED PROGRAMMING

A Load Configuration or Load Data for Program Memory command must be given before every Begin Programming command. Programming of the addressed memory will begin after this command is received. An internal timing mechanism executes the write. The user must allow for the program cycle time, TPINT, in order for the programming to complete.

The End Externally Timed Programming command is not needed when the Begin Internally Timed Programming is used to start the programming.

The program memory address that is being programmed is not erased prior to being programmed (see Figure 4-6).

FIGURE 4-6: BEGIN INTERNALLY TIMED PROGRAMMING

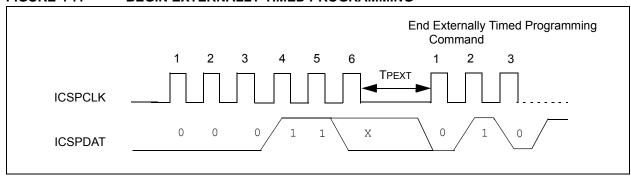


4.3.7 BEGIN EXTERNALLY TIMED PROGRAMMING

A Load Configuration or Load Data for Program Memory command must be given before every Begin Programming command. Programming of the addressed memory will begin after this command is received. To complete the programming, the End Externally Timed Programming command must be sent in the specified time window defined by TPEXT (see Figure 4-7).

Externally timed writes are not supported for Configuration and Calibration bits. Any externally timed write to the Configuration or Calibration Word will have no effect on the targeted word.

FIGURE 4-7: BEGIN EXTERNALLY TIMED PROGRAMMING

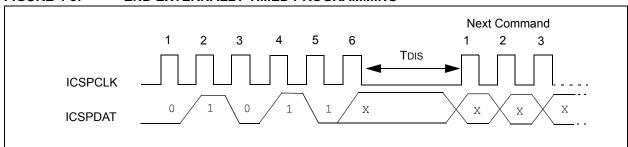


4.3.8 END EXTERNALLY TIMED PROGRAMMING

This command is required after a Begin Externally Timed Programming command is given. This command must be sent within the time window specified by TPEXT after the Begin Externally Timed Programming command is sent.

After sending the End Externally Timed Programming command, an additional delay (TDIS) is required before sending the next command. This delay is longer than the delay ordinarily required between other commands (see Figure 4-8).

FIGURE 4-8: END EXTERNALLY TIMED PROGRAMMING



4.3.9 BULK ERASE PROGRAM MEMORY

The Bulk Erase Program Memory command performs two different functions dependent on the current state of the address.

Address 0000h-7FFFh:

Program Memory is erased Configuration Words are erased

Address 8000h-8008h:

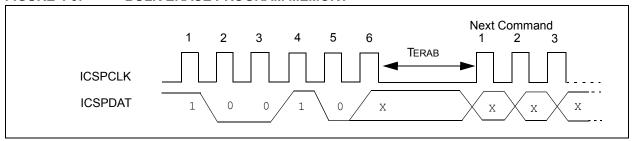
Program Memory is erased Configuration Words are erased User ID Locations are erased

A Bulk Erase Program Memory command should not be issued when the address is greater than 8008h.

After receiving the Bulk Erase Program Memory command, the erase will not complete until the time interval, TERAB, has expired.

Note: The code protection Configuration bit $\overline{(CP)}$ has no effect on the Bulk Erase Program Memory command.

FIGURE 4-9: BULK ERASE PROGRAM MEMORY



4.3.10 ROW ERASE PROGRAM MEMORY

The Row Erase Program Memory command will erase an individual row. Refer to Table 4-2 for row sizes of specific devices and the PC bits used to address them. If the program memory is code-protected, the Row Erase Program Memory command will be ignored. When the address is 8000h-8008h, the Row Erase Program Memory command will only erase the user ID locations regardless of the setting of the $\overline{\text{CP}}$ Configuration bit.

After receiving the Row Erase Program Memory command, the erase will not complete until the time interval, TERAR, has expired (see Figure 4-10).

FIGURE 4-10: ROW ERASE PROGRAM MEMORY

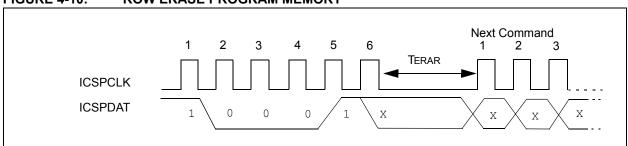


TABLE 4-2: PROGRAMMING ROW AND LATCH SIZES

Devices	PC	Erase Row Size (Number of 14-bit Words)	Write Row Size (Number of 14-bit Latches)
PIC16F1703			
PIC16F1707	445.55	40	40
PIC16LF1703	<15:5>	16	16
PIC16LF1707			
PIC16F1704			
PIC16F1705			
PIC16F1708			
PIC16F1709	<15:5>	32	32
PIC16LF1704			
PIC16LF1705			
PIC16LF1708			
PIC16LF1709			

5.0 PROGRAMMING ALGORITHMS

The devices use internal latches to temporarily store the 14-bit words used for programming. Refer to Table 4-2 for specific latch information. The data latches allow the user to write the program words with a single Begin Externally Timed Programming or Begin Internally Timed Programming command. The Load Program Data or the Load Configuration command is used to load a single data latch. The data latch will hold the data until the Begin Externally Timed Programming or Begin Internally Timed Programming command is given.

The data latches are aligned with the LSbs of the address. The PS address bits indicated in Table 4-2 at the time the Begin Externally Timed Programming or Begin Internally Timed Programming command is given will determine which memory row is written. Writes cannot cross a physical row boundary. For example, attempting to write from address 0002h-0021h in a 32-latch device will result in data being written to 0020h-003Fh.

If more than the maximum number of latches are written without a Begin Externally Timed Programming or Begin Internally Timed Programming command, the data in the data latches will be overwritten. The following figures show the recommended flowcharts for programming.

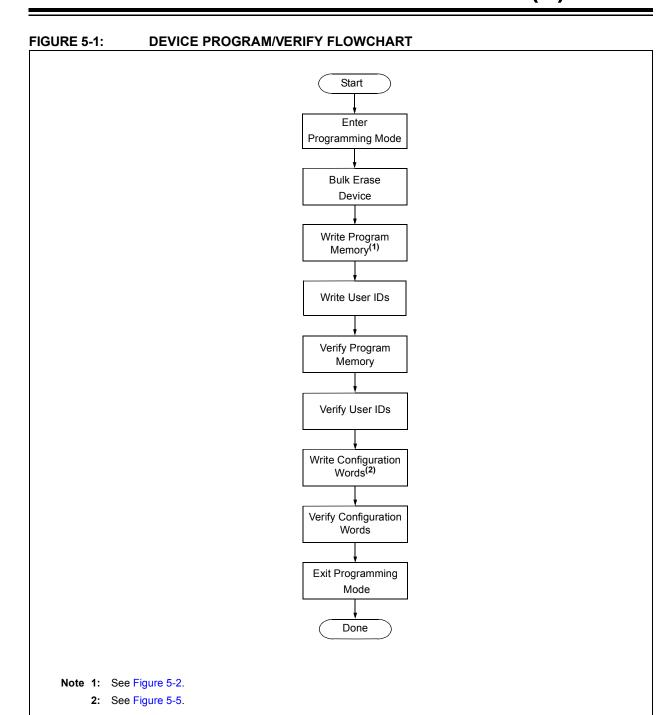
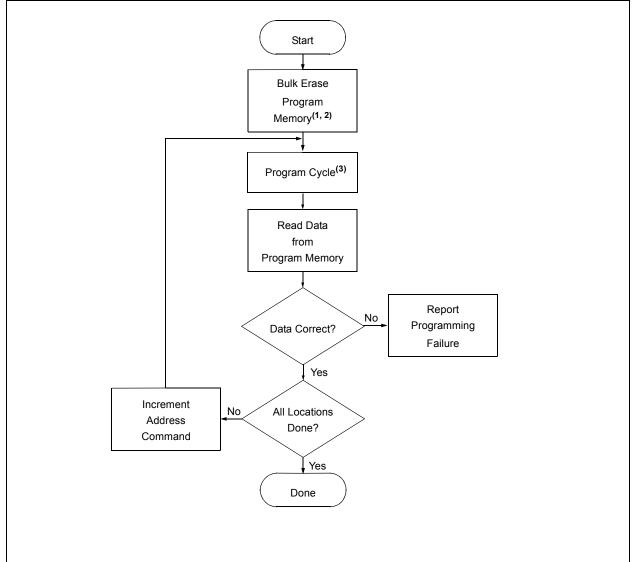
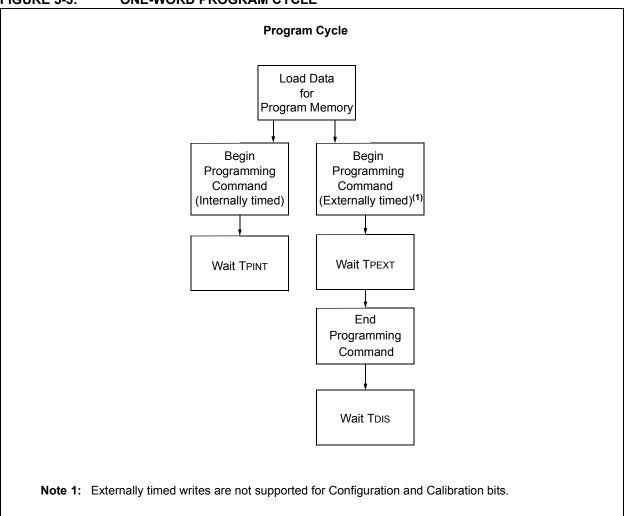


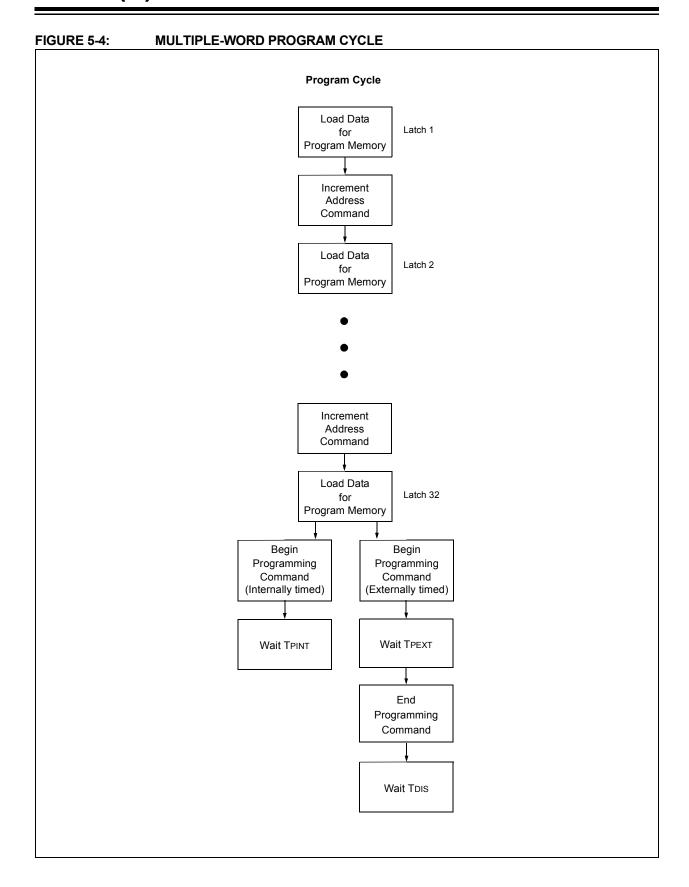
FIGURE 5-2: PROGRAM MEMORY FLOWCHART



- Note 1: This step is optional if the device has already been erased or has not been previously programmed.
 - 2: If the device is code-protected or must be completely erased, then Bulk Erase the device per Figure 5-6.
 - 3: See Figure 5-3 or Figure 5-4.

FIGURE 5-3: ONE-WORD PROGRAM CYCLE





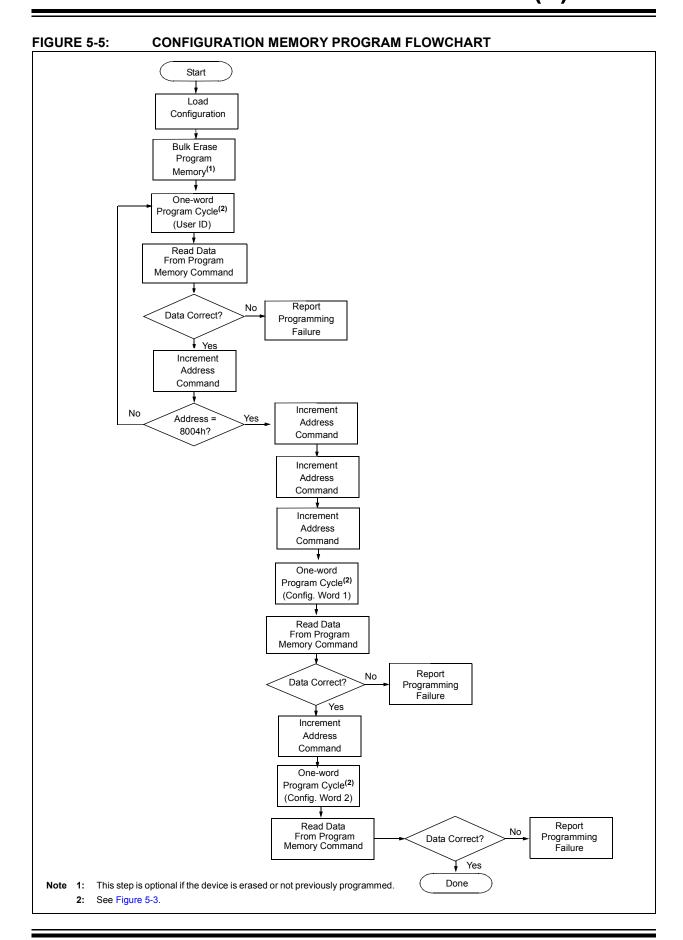
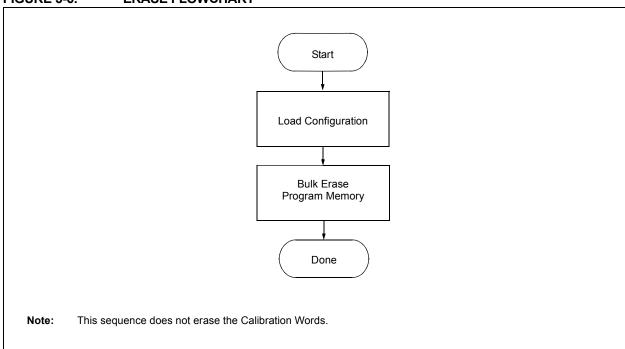


FIGURE 5-6: ERASE FLOWCHART



6.0 CODE PROTECTION

Code protection is controlled using the $\overline{\text{CP}}$ bit in Configuration Word 1. When code protection is enabled, all program memory locations (0000h-7FFFh) read as '0'. Further programming is disabled for the program memory (0000h-7FFFh). Program memory can still be programmed and read during program execution

The user ID locations and Configuration Words can be programmed and read out regardless of the code protection settings.

6.1 Program Memory

Code protection is enabled by programming the \overline{CP} bit in Configuration Word 1 register to '0'.

The only way to disable code protection is to use the Bulk Erase Program Memory command.

7.0 HEX FILE USAGE

In the hex file there are two bytes per program word stored in the Intel[®] INHX32 hex format. Data is stored LSB first, MSB second. Because there are two bytes per word, the addresses in the hex file are 2x the address in program memory. (Example: The Configuration Word 1 is stored at 8007h. In the hex file this will be referenced as 1000Eh-1000Fh).

7.1 Configuration Word

To allow portability of code, it is strongly recommended that the programmer is able to read the Configuration Words and user ID locations from the hex file. If the Configuration Words information was not present in the hex file, a simple warning message may be issued. Similarly, while saving a hex file, Configuration Words and user ID information should be included.

7.2 Device ID

If a device ID is present in the hex file at 1000Ch-1000Dh (8006h on the part), the programmer should verify the device ID against the value read from the part. On a mismatch condition, the programmer should generate a warning message.

7.3 Checksum Computation

The checksum is calculated by $\underline{\text{two}}$ different methods dependent on the setting of the $\overline{\text{CP}}$ Configuration bit.

TABLE 7-1: CONFIGURATION WORD MASK VALUES

Device	Config. Word 1 Mask	Config. Word 2 Mask							
PIC16F1703	0EFBh	3F87h							
PIC16LF1703	0EFBh	3F87h							
PIC16F1704	3EFFh	3F87h							
PIC16LF1704	3EFFh	3F87h							
PIC16F1705	3EFFh	3F87h							
PIC16LF1705	3EFFh	3F87h							
PIC16F1707	0EFBh	3F87h							
PIC16LF1707	0EFBh	3F87h							
PIC16F1708	3EFFh	3F87h							
PIC16LF1708	3EFFh	3F87h							
PIC16F1709	3EFFh	3F87h							
PIC16LF1709	3EFFh	3F87h							

7.3.1 PROGRAM CODE PROTECTION DISABLED

With the program code protection disabled, the checksum is computed by reading the contents of the PIC16(L)F170X program memory locations and adding up the program memory data starting at address 0000h, up to the maximum user addressable location (e.g., FFFh for the PIC16F1704). Any Carry bits exceeding 16 bits are ignored. Additionally, the relevant bits of the Configuration Words are added to the checksum. All unimplemented Configuration bits are masked to '0'.

7.3.2 PROGRAM CODE PROTECTION ENABLED

When the MPLAB IDE check box for Configure->ID Memory...-> Use Unprotected Checksum is checked, then the 16-bit checksum of the equivalent unprotected device is computed and stored in the user ID. Each nibble of the unprotected checksum is stored in the Least Significant nibble of each of the four user ID locations. The Most Significant checksum nibble is stored in the user ID at location 8000h, the second Most Significant nibble is stored at location 8001h, and so forth for the remaining nibbles and ID locations. The protected checksums in Table 7-2 assume that the Use Unprotected Checksum box is checked.

The checksum of a code-protected device is computed in the following manner: the Least Significant nibble of each user ID is used to create a 16-bit value. The Least Significant nibble of user ID location 8000h is the Most Significant nibble of the 16-bit value. The Least Significant nibble of user ID location 8001h is the second Most Significant nibble, and so forth for the remaining user IDs and 16-bit value nibbles. The resulting 16-bit value is summed with the Configuration Words. All unimplemented Configuration bits are masked to '0'.

TABLE 7-2: CHECKSUMS

.,									
	C	Config2		Checksum					
Device					Mask	Unp	rotected	Code-protected	
	Unprotected	Protected	Mask	Word		Blank	00AAh First and Last	Blank	00AAh First and Last
PIC16F1703	3FFFh	3F7Fh	0EFBh	3FFFh	3F87h	4682h	C7D8h	9484h	15DAh
PIC16F1704	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	6E86h	EFDCh	EC8Ch	6DE2h
PIC16F1705	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	5E86h	DFDCh	DC8Ch	5DE2h
PIC16F1707	3FFFh	3F7Fh	0EFBh	3FFFh	3F87h	4682h	C7D8h	9484h	15DAh
PIC16F1708	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	6E86h	EFDCh	EC8Ch	6DE2h
PIC16F1709	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	5E86h	DFDCh	DC8Ch	5DE2h
PIC16LF1703	3FFFh	3F7Fh	0EFBh	3FFFh	3F87h	4682h	C7D8h	9484h	15DAh
PIC16LF1704	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	6E86h	EFDCh	EC8Ch	6DE2h
PIC16LF1705	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	5E86h	DFDCh	DC8Ch	5DE2h
PIC16LF1707	3FFFh	3F7Fh	0EFBh	3FFFh	3F87h	4682h	C7D8h	9484h	15DAh
PIC16LF1708	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	6E86h	EFDCh	EC8Ch	6DE2h
PIC16LF1709	3FFFh	3F7Fh	3EFFh	3FFFh	3F87h	5E86h	DFDCh	DC8Ch	5DE2h

8.0 ELECTRICAL SPECIFICATIONS

Refer to device specific data sheet for absolute maximum ratings.

TABLE 8-1: AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY MODE

AC/DC	CHARACTERISTICS		Standard O Production t								
Sym.	Characteristic	Min.	Тур.	Max.	Units	Conditions/Comments					
	Programming Supply Voltages and Currents										
	Supply Voltage	PIC16LF170X	1.80		3.60	V	Fosc ≤ 16 MHz				
VDD	(VDDMIN ⁽²⁾ , VDDMAX)		2.70	_	3.60	V	Fosc ≤ 32 MHz				
VDD		PIC16F170X	2.30	_	5.50	V	Fosc ≤ 16 MHz				
			2.70		5.50	V	Fosc ≤ 32 MHz				
VPEW	Read/Write and Row Erase oper	ations	VDDMIN	_	VDDMAX	V					
VBE	Bulk Erase operations	2.7	_	VDDMAX	V						
Iddi	Current on VDD, Idle		_	_	1.0	mA					
IDDP	Current on VDD, Programming		_	_	3.0	mA					
	VPP										
IPP	Current on MCLR/VPP		_	_	600	μΑ					
VIHH	High voltage on MCLR/VPP for Program/Verify mode entry		8.0	_	9.0	V					
TVHHR	MCLR rise time (VIL to VIHH) for Program/Verify mode entry		_	_	1.0	μS					
	I/O pins		<u>l</u>	ı							
VIH	(ICSPCLK, ICSPDAT, MCLR/VP) input high level	0.8 VDD	_	_	V					
VIL	(ICSPCLK, ICSPDAT, MCLR/VP	_	_	0.2 VDD	V						
Vон	ICSPDAT output high level	VDD-0.7 VDD-0.7 VDD-0.7	_	_	V	IOH = 3.5 mA, VDD = 5V IOH = 3 mA, VDD = 3.3V IOH = 2 mA, VDD = 1.8V					
	ICSPDAT output low level		755 (Vss+0.6		IOH = 8 mA, VDD = 5V				
Vol		_	_	Vss+0.6 Vss+0.6	V	IOH = 6 mA, VDD = 3.3V IOH = 3 mA, VDD = 1.8V					
VBOR	Brown-out Reset Voltage: BORV = 0 (high	_	2.70	_	V	PIC16(L)F170X					
	BORV = 1 (low	_	2.40	_	V	PIC16F170X					
		_	1.90	_	V	PIC16LF170X					
			ng Mode Ent	ry and Exi	it						
TENTS	Programing mode entry setup tir ICSPDAT setup time before VDD	or MCLR↑	100	_	_	ns					
TENTH	Programing mode entry hold tim ICSPDAT hold time after VDD or	MCLR [↑]	250	_	_	μS					
		Seria	l Program/Ve	erify							
TCKL	Clock Low Pulse Width		100			ns					
	Clock High Pulse Width		100	_		ns					
TDS	Data in setup time before clock↓		100	_		ns					
TDH	Data in hold time after clock↓		100	_	–	ns					
Tco	Clock↑ to data out valid (during a Read Data command)		0	_	80	ns					
TLZD	Clock↓ to data low-impedance (o Read Data command)	-	0	_	80	ns					
THZD	Clock↓ to data high-impedance (Read Data command)	during a	0	_	80	ns					

Note 1: Externally timed writes are not supported for Configuration and Calibration bits.

^{2:} Bulk-erased devices default to brown-out enabled. VDDMIN is 2.85 volts when performing low-voltage programming on a bulk-erased device, to ensure that the device is not held in Brown-out Reset.

TABLE 8-1: AC/DC CHARACTERISTICS TIMING REQUIREMENTS FOR PROGRAM/VERIFY MODE

AC/DC CHARACTERISTICS		Standard Operating Conditions Production tested at 25°C						
Sym.	Characteristics	Min.	Тур.	Max.	Units	Conditions/Comments		
TDLY	Data input not driven to next clock input (delay required between command/data or command/ command)	1.0	_	_	μ\$			
TERAB	Bulk Erase cycle time	_	_	5	ms			
TERAR	Row Erase cycle time	_	_	2.5	ms			
TPINT	Internally timed programming operation time	_	_	2.5 5	ms ms	Program memory Configuration Words		
TPEXT	Externally timed programming pulse	1.0	_	2.1	ms	Note 1		
TDIS	Time delay from program to compare (HV discharge time)	300	_	_	μS			
TEXIT	Time delay when exiting Program/Verify mode	1	_	_	μS			

Note 1: Externally timed writes are not supported for Configuration and Calibration bits.

8.1 AC Timing Diagrams

FIGURE 8-1: PROGRAMMING MODE ENTRY – VDD FIRST

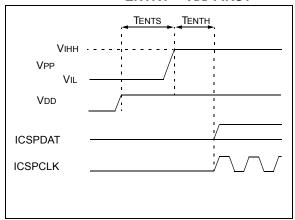


FIGURE 8-2: PROGRAMMING MODE ENTRY – VPP FIRST

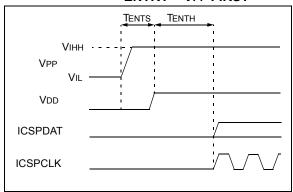


FIGURE 8-3: PROGRAMMING MODE EXIT – VPP LAST

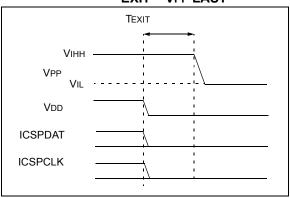
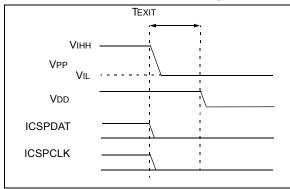


FIGURE 8-4: PROGRAMMING MODE EXIT – VDD LAST



^{2:} Bulk-erased devices default to brown-out enabled. VDDMIN is 2.85 volts when performing low-voltage programming on a bulk-erased device, to ensure that the device is not held in Brown-out Reset.

FIGURE 8-5: CLOCK AND DATA TIMING

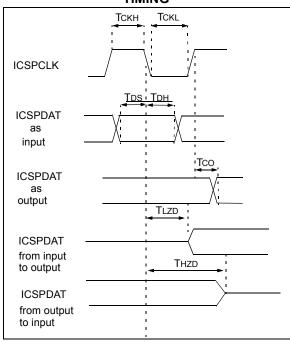


FIGURE 8-6: WRITE COMMAND – PAYLOAD TIMING

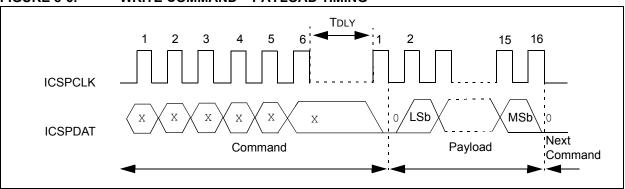


FIGURE 8-7: READ COMMAND – PAYLOAD TIMING

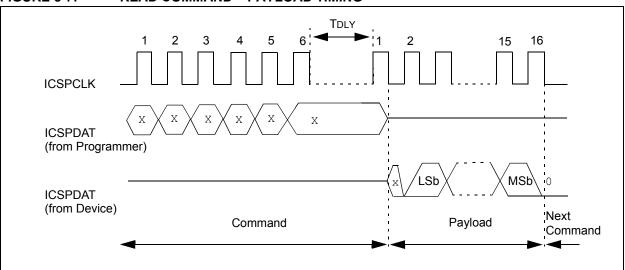


FIGURE 8-8: LVP ENTRY (POWERING UP)

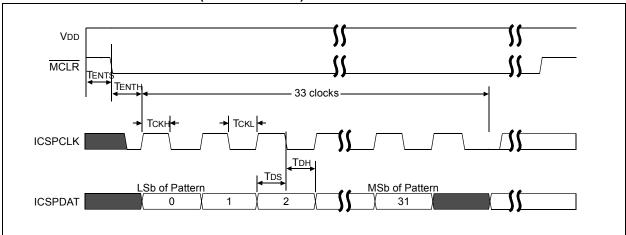
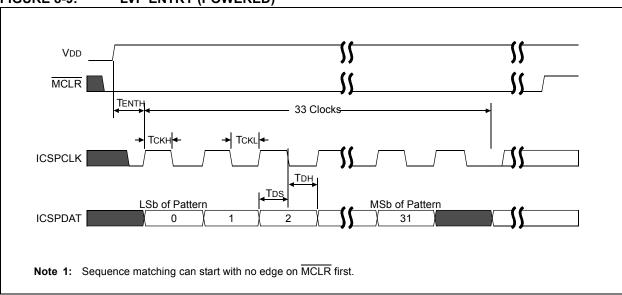


FIGURE 8-9: LVP ENTRY (POWERED)



APPENDIX A: REVISION HISTORY

Revision A (02/2013)

Initial release of this document.

Revision B (06/2013)

Changed PIC16(L)F1704/8 to PIC16(L)F170x in the document title; Added PIC16(L)F1703/7 and PIC16(L)F1705/9 devices.

NOTES:

Note the following details of the code protection feature on Microchip devices:

- · Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our
 knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data
 Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV = ISO/TS 16949=

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MTP, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

Analog-for-the-Digital Age, Application Maestro, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, SQI, Serial Quad I/O, Total Endurance, TSHARC, UniWinDriver, WiperLock, ZENA and Z-Scale are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

GestIC and ULPP are registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2013, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

ISBN: 9781620772898

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



Worldwide Sales and Service

AMERICAS

Corporate Office 2355 West Chandler Blvd.

Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support

Web Address: www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago Itasca, IL

Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Indianapolis Noblesville, IN

Tel: 317-773-8323 Fax: 317-773-5453

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario,

Canada

Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

China - Chengdu Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongging Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hangzhou Tel: 86-571-2819-3187 Fax: 86-571-2819-3189

China - Hong Kong SAR Tel: 852-2943-5100 Fax: 852-2401-3431

China - Nanjing Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

China - Qingdao Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen Tel: 86-755-8864-2200 Fax: 86-755-8203-1760

China - Wuhan Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore Tel: 91-80-3090-4444

Fax: 91-80-3090-4123 India - New Delhi Tel: 91-11-4160-8631

Fax: 91-11-4160-8632 India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Osaka Tel: 81-6-6152-7160 Fax: 81-6-6152-9310

Japan - Tokyo Tel: 81-3-6880- 3770 Fax: 81-3-6880-3771

Korea - Daegu Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu Tel: 886-3-5778-366 Fax: 886-3-5770-955

Taiwan - Kaohsiung Tel: 886-7-213-7828 Fax: 886-7-330-9305

Taiwan - Taipei Tel: 886-2-2508-8600 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen Tel: 45-4450-2828

Fax: 45-4485-2829

France - Paris Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich Tel: 49-89-627-144-0

Fax: 49-89-627-144-44 Italy - Milan Tel: 39-0331-742611

Fax: 39-0331-466781 Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

UK - Wokingham Tel: 44-118-921-5869 Fax: 44-118-921-5820

11/29/12